

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
60V	13mΩ@10V	8A
	18mΩ@4.5V	

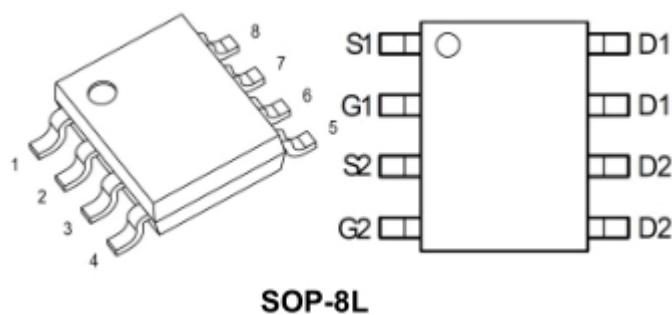
## Feature

- $V_{DS} = 60V, I_D = 8A$
- $R_{DS(ON)} < 18m\Omega$  @  $V_{GS}=10V$  (Typ:13mΩ)
- $R_{DS(ON)} < 26m\Omega$  @  $V_{GS}=4.5V$  (Typ:18mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

## Applications

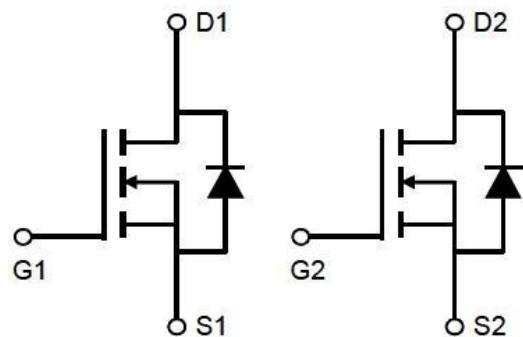
- Power switching application
- Load switch

## Package

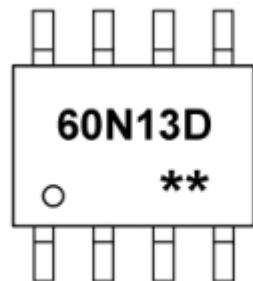


SOP-8L

## Circuit diagram



## Marking



**60N13D** : Product code  
**\*\*** : Week code.

## Absolute maximum ratings

( $T_a=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	8	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	32	A
Maximum Power Dissipation	$P_D$	1.4	W
Thermal Resistance, Junction-to-Case <sup>(2)</sup>	$R_{\theta JC}$	1.3	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_{STG}, T_J$	-55 To 150	$^\circ\text{C}$



ZL MOSFET

ZL60N13DN

## Electrical characteristics

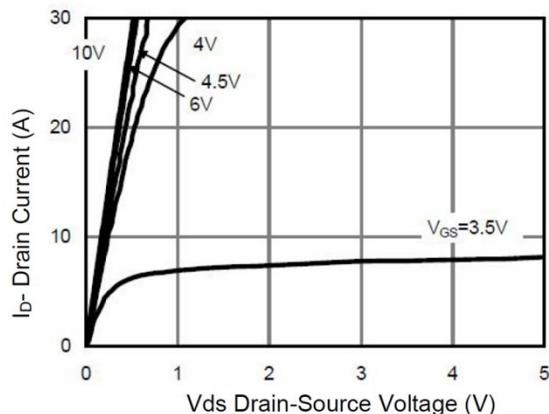
(T<sub>A</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V			1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	uA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.6	2.5	V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 8A		12	16	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 8A		15	22	
<b>Dynamic and Switching Characteristics<sup>(4)</sup></b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz		1600		pF
Output capacitance	C <sub>oss</sub>			112		
Reverse transfer capacitance	C <sub>rss</sub>			98		
<b>Switching Characteristics<sup>(4)</sup></b>						
Turn-on Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> = 1Ω, V <sub>GS</sub> =10V, R <sub>GEN</sub> = 3Ω		7		nS
Turn-on Rise Time	T <sub>r</sub>			5.5		
Turn-Off Delay Time	T <sub>d(off)</sub>			29		
Turn-Off Fall Time	t <sub>f</sub>			4.5		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V , I <sub>D</sub> = 8A, V <sub>GS</sub> =10V		38.5		pF
Gate-Source Charge	Q <sub>gs</sub>			4.7		
Gate-Drain Charge	Q <sub>gd</sub>			10.3		
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V ,I <sub>S</sub> =8A			1.2	V

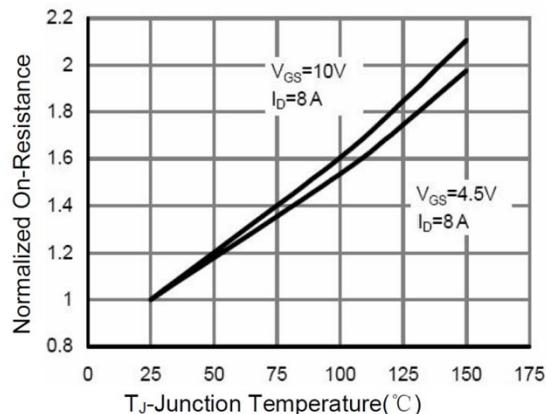
### Note:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

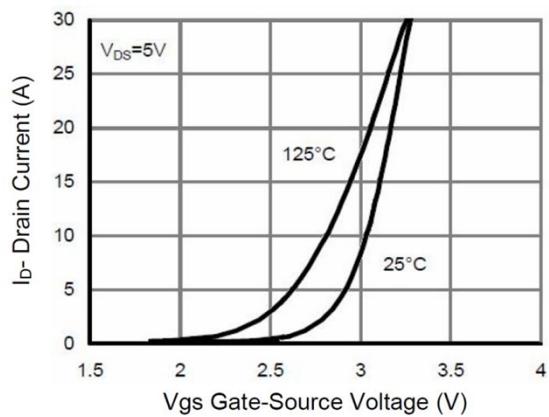
## Typical Characteristics



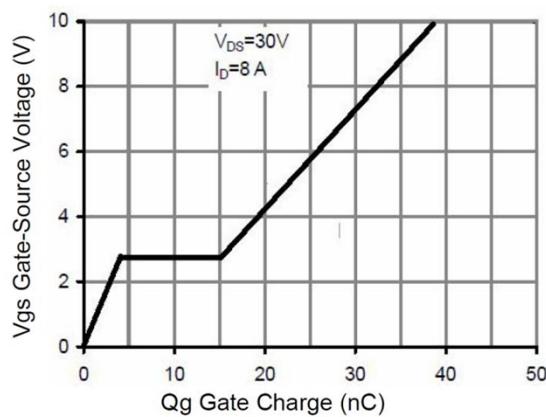
**Figure 1 Output Characteristics**



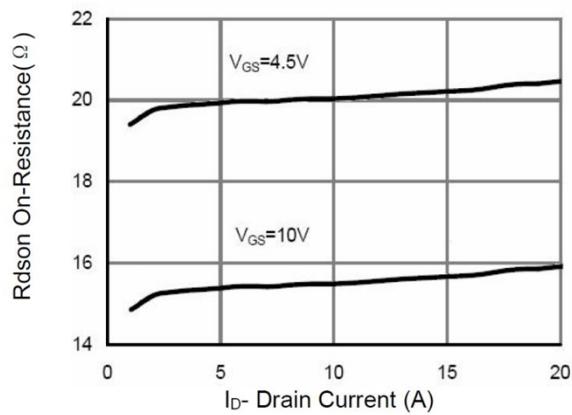
**Figure 4 Rdson-JunctionTemperature**



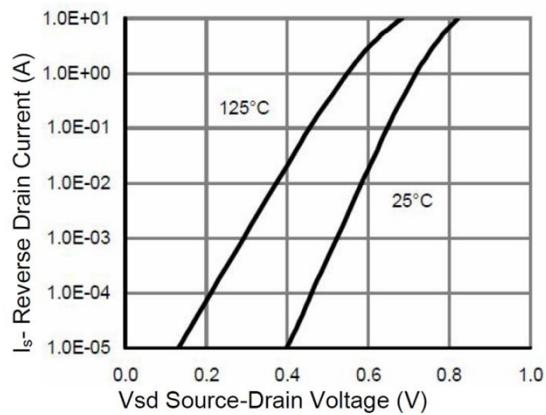
**Figure 2 Transfer Characteristics**



**Figure 5 Gate Charge**



**Figure 3 Rdson- Drain Current**



**Figure 6 Source- Drain Diode Forward**



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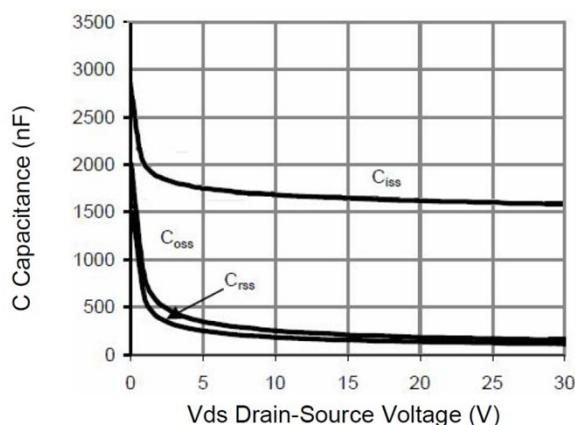


Figure 7 Capacitance vs Vds

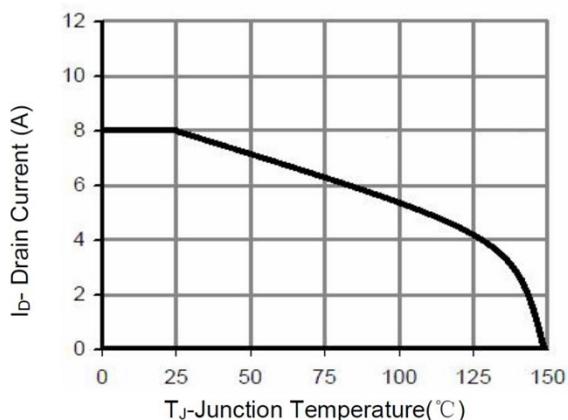


Figure 9 Current De-rating

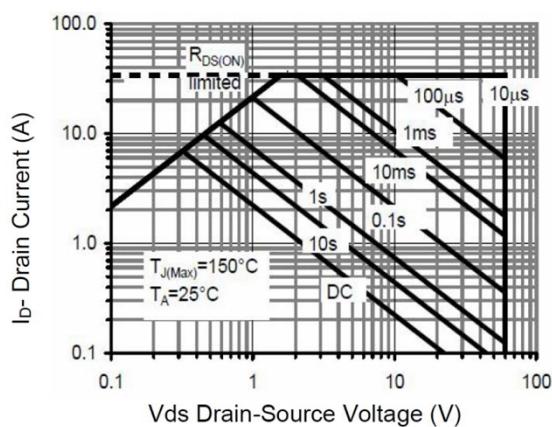


Figure 8 Safe Operation Area

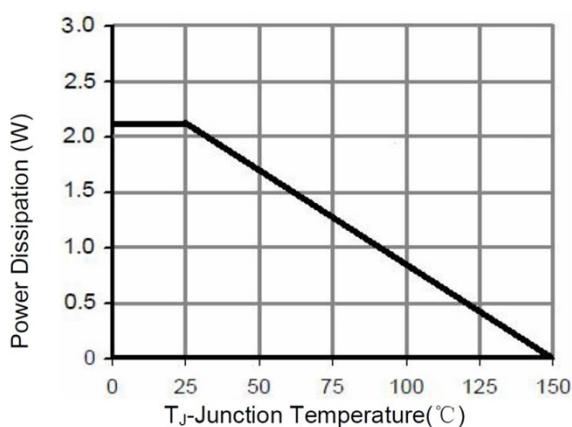


Figure 10 Power De-rating

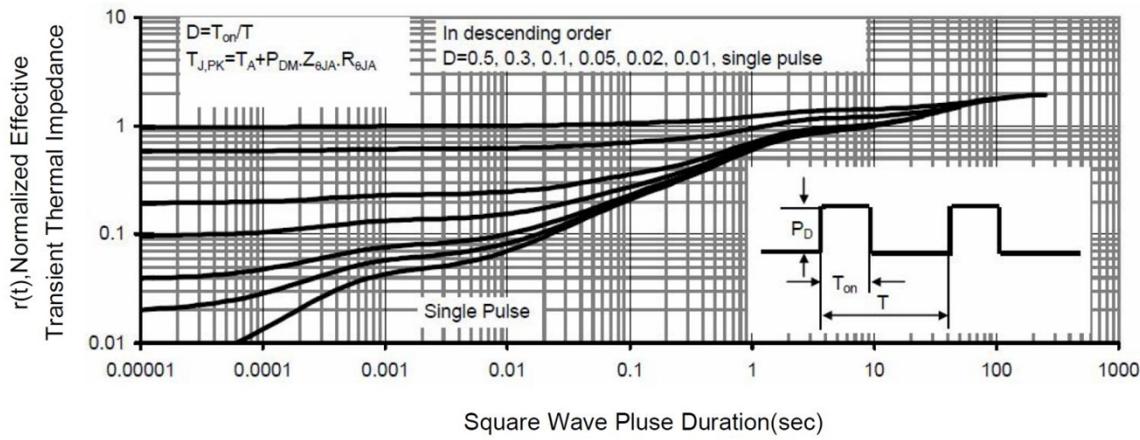
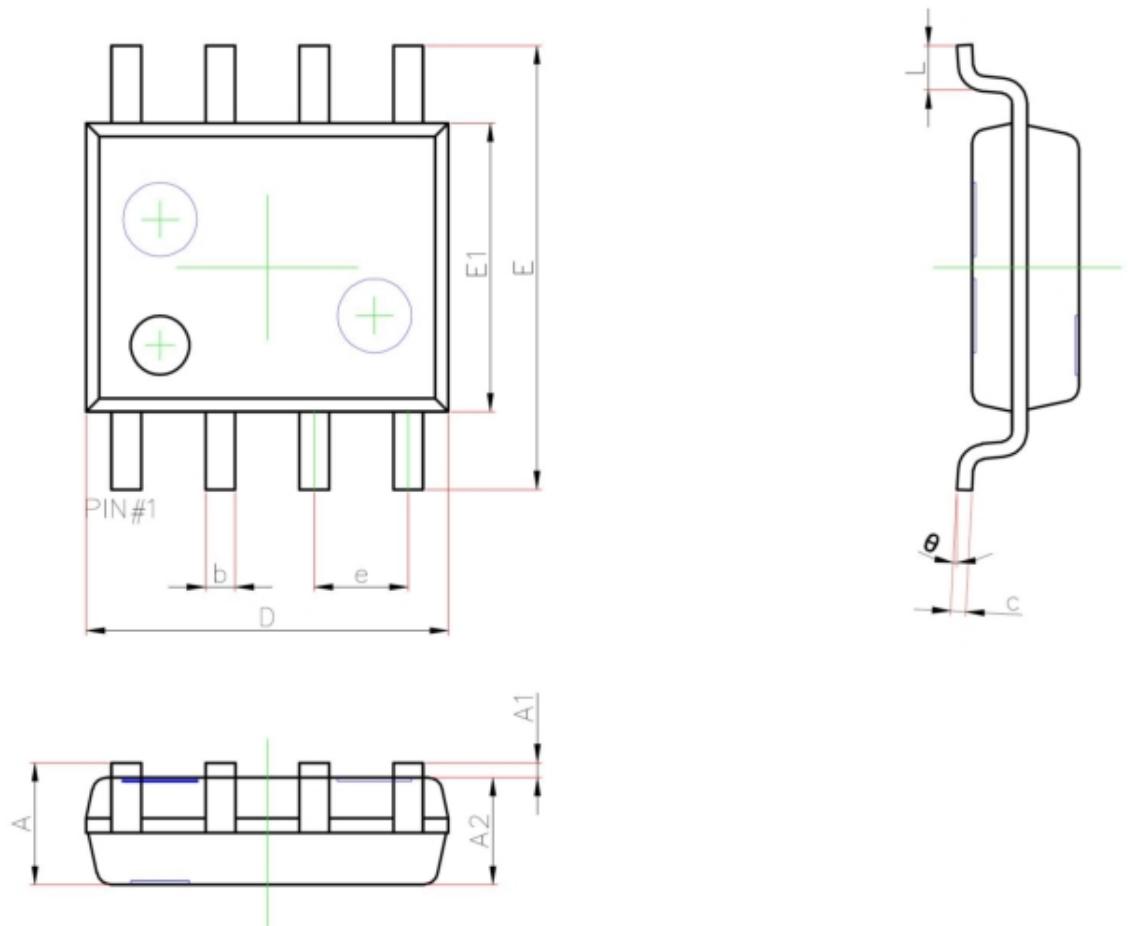


Figure 11 Normalized Maximum Transient Thermal Impedance

## SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
$\theta$	0°	8°